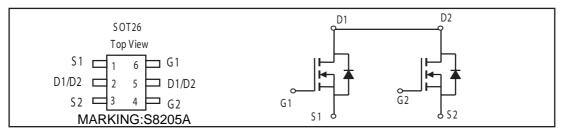


Dual N-Channel Enhancement Mode Field Effect Transistor

PRODU	PRODUCT SUMMARY			
VDSS	ID	R DS (ON) (m ohm) Max		
20V	5A	$25@V_{GS} = 4.5 \text{ V} \\ 40@V_{GS} = 2.5 \text{ V}$		

FEATURES

- Super high dense cell design for low R DS(ON).
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS (T_A=25 °C unless otherwise noted)

Parameter	S ymbol	Limit	Unit
Drain-S ource Voltage	VDS	20	V
Gate-Source Voltage	VGS	±12	V
Drain Current-Continuous @ T₃=25°C -Pulsed ^b	ID	5	А
	IDM	25	А
Drain-Source Diode Forward Current ^a	Is	2	А
Maximum Power Dissipation ^a	PD	1.25	W
Operating Junction and Storage Temperature Range	TJ, TSTG	-55 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient ^a	R ∂JA	100	°C/W
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ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

Parameter	S ymbol	Condition	Min	Тур	Max	Unit		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BVDSS	VGS = 0V, ID = 250uA	20			٧		
Zero Gate Voltage Drain Current	loss	VDS =16V, VGS =0V			1	uA		
Gate-Body Leakage	lgss	$VGS = \pm 12V$ $DS = 0V$			±100	nA		
ON CHARACTERISTICS b								
Gate Threshold Voltage	VGS(th)	V DS = V GS , ID = 250uA	0.5	0.8	1.0	٧		
Dunin Course On Chata Davietanea	D	$V_{GS} = 4.0V, I_{D} = 5A$		22	25	m ohm		
Drain-Source On-State Resistance	R DS (ON)	VGS =2.5V, ID = 4A		38	40	m ohm		
Forward Transconductance	g _{FS}	V ds = 5V, Id =5A		13		S		
DYNAMIC CHARACTERISTICS C								
Input Capacitance	Ciss	V 0V V 0V		800		РF		
rain-Source Breakdown Voltage Pro Gate Voltage Drain Current Pate-Body Leakage IN CHARACTERISTICS Pate Threshold Voltage Prain-Source On-State Resistance Provided Transconductance Provided Transconductance	Coss	V DS = 8V, V GS = 0V f = 1.0 MHz		155		РF		
Reverse Transfer Capacitance	Crss	1 110111112		125		РF		
Turn-On Delay Time	tD(ON)	V _{DD} = 10V,		18.3		ns		
Rise Time	tr	ID = 1A, VGEN = 4.0V,		4.8		ns		
Turn-Off Delay Time	tD(OFF)	$R_L = 10 \text{ ohm}$		43.5		ns		
Fall Time	tf	RGEN = 10 ohm		20		ns		
Total Gate Charge	Qg			11		nC		
Gate-Source Charge	Qgs	VDS =10V, ID = 4A, VGS =4.0V		2.2		nC		
Gate-Drain Charge	Qgd	¥ 03 — 1.0 ¥		2.5		nC		



ELECTRICAL CHARACTERISTICS (T_A=25 °C unless otherwise noted)

Parameter	S ymbol	Condition	Min	Тур	Max	Unit	
DRAIN-SOURCE DIODE CHARACTERISTICS b							
Diode Forward Voltage	Vsd	VGS = 0V, IS = 1.7 A	0.42		1.28	V	

Notes

- a.S urface Mounted on FR4 Board, t≤10sec.
- b.Pulse Test:Pulse Width \leq 300us, Duty Cycle \leq 2%.
- c.Guaranteed by design, not subject to production testing.

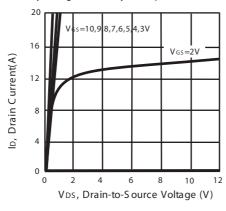


Figure 1. Output Characteristics

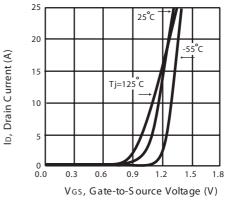


Figure 2. Transfer Characteristics

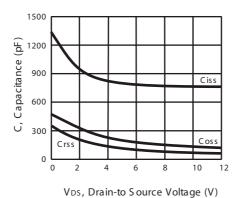


Figure 3. Capacitance

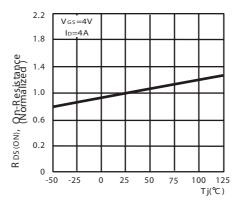
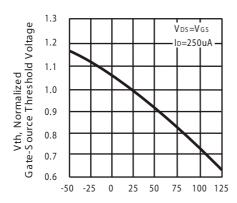
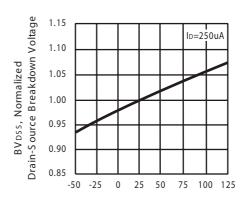


Figure 4. On-Resistance Variation with Temperature



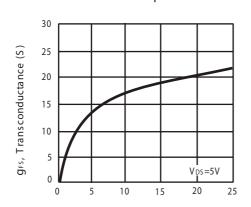


Tj, Junction Temperature (°C)



Tj, Junction Temperature (°C)

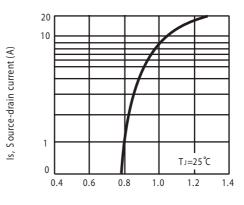
with Temperature



IDS, Drain-Source Current (A) Figure 7. Transconductance Variation

with Drain Current

Figure 6. Breakdown Voltage Variation with Temperature



VsD, Body Diode Forward Voltage (V)

Figure 8. Body Diode Forward Voltage Variation with Source Current

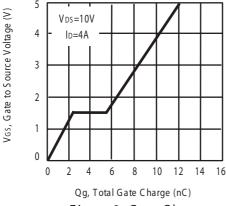
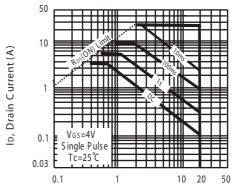


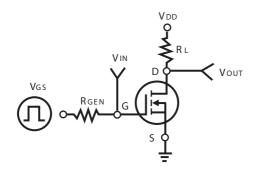
Figure 9. Gate Charge



VDS, Drain-Source Voltage (V)

Figure 10. Maximum Safe Operating Area





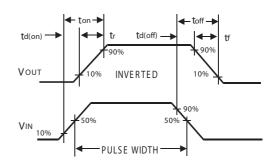


Figure 11. Switching Test Circuit

Figure 12. Switching Waveforms

